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0.5 Ω CMOS 1.65 V TO 3.6 V 4-Channel Multiplexer

Data Sheet **ADG804**

FEATURES

0.5 Ω typical on resistance
0.8 Ω maximum on resistance at 125°C
1.65 V to 3.6 V operation
Automotive temperature range: –40°C to +125°C
High current carrying capability: 300 mA continuous
Rail-to-rail switching operation
Fast switching times <25 ns
Typical power consumption (<0.1 µW)

APPLICATIONS

MP3 players
Power routing
Battery-powered systems
PCMCIA cards
Cellular phones
Modems
Audio and video signal routing
Communication systems

GENERAL DESCRIPTION

The ADG804 is a low voltage 4-channel CMOS multiplexer comprising four single channels. This device offers ultralow on resistance of less than 0.8 Ω over the full temperature range. The digital inputs can handle 1.8 V logic with a 2.7 V to 3.6 V supply.

The ADG804 switches one of four inputs to a common output, D, as determined by the 3-bit binary address lines, A0, A1, and EN. A Logic 0 on the EN pin disables the device. The ADG804 has break-before-make switching.

The ADG804 is fully specified for 3.3 V, 2.5 V, and 1.8 V supply operation. It is available in a 10-lead MSOP package.

FUNCTIONAL BLOCK DIAGRAM

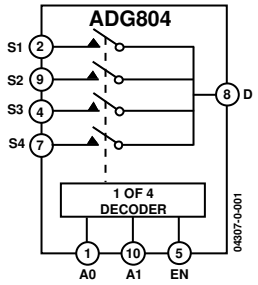

Figure 1.

PRODUCT HIGHLIGHTS

1. <0.8 Ω over full temperature range of –40°C to +125°C.
2. Single 1.65 V to 3.6 V operation.
3. Operational with 1.8 V CMOS logic.
4. High current handling capability (300 mA continuous current at 3.3 V).
5. Low THD + N (0.02% typ).
6. Small 10-lead MSOP package.

Rev. A

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ADG804* PRODUCT PAGE QUICK LINKS

Last Content Update: 02/23/2017

COMPARABLE PARTS

View a parametric search of comparable parts.

EVALUATION KITS

- Evaluation Board for 10-Lead MSOP Devices in the Switches and Multiplexers Portfolio

DOCUMENTATION

Application Notes

- AN-1024: How to Calculate the Settling Time and Sampling Rate of a Multiplexer

Data Sheet

- ADG804: 0.5 Ω CMOS 1.65 V TO 3.6 V 4-Channel Multiplexer Data Sheet

User Guides

- UG-1037: Evaluation Board for 10-Lead MSOP Devices in the Switches and Multiplexers Portfolio

REFERENCE MATERIALS

Product Selection Guide

- Switches and Multiplexers Product Selection Guide

DESIGN RESOURCES

- ADG804 Material Declaration
- PCN-PDN Information
- Quality And Reliability
- Symbols and Footprints

DISCUSSIONS

View all ADG804 EngineerZone Discussions.

SAMPLE AND BUY

Visit the product page to see pricing options.

TECHNICAL SUPPORT

Submit a technical question or find your regional support number.

DOCUMENT FEEDBACK

Submit feedback for this data sheet.

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Updated Outline Dimensions 13
Changes to Ordering Guide 13

4/04—Revision 0: Initial Version

SPECIFICATIONS

V_{DD} = 2.7 V to 3.6 V, GND = 0 V, unless otherwise noted.[1]

Table 1.

Parameter	+25°C	−40°C to +85°C	−40°C to +125°C	Unit	Test Conditions/Comments
ANALOG SWITCH					
Analog Signal Range			0 V to V_{DD}	V	
On Resistance (R_{ON})	0.5			Ω typ	V_{DD} = 2.7 V; V_S = 0 V to V_{DD}, I_S = 10 mA; Figure 18
	0.65	0.75	0.8	Ω max	
On Resistance Match between	0.04			Ω typ	V_{DD} = 2.7 V; V_S = 0.65 V, I_S = 10 mA
Channels (ΔR_{ON})		0.075	0.08	Ω max	
On Resistance Flatness ($R_{FLAT(ON)}$)	0.1			Ω typ	V_{DD} = 2.7 V; V_S = 0 V to V_{DD},
		0.15	0.16	Ω max	I_S = 10 mA
LEAKAGE CURRENTS					V_{DD} = 3.6 V
Source Off Leakage I_S (OFF)	±0.1			nA typ	V_S = 1 V/2.6 V; V_D = 2.6 V/1 V; Figure 19
	±2			nA max	
Drain Off Leakage I_D (OFF)	±0.1			nA typ	V_S = 1 V/2.6 V; V_D = 2.6 V/1 V; Figure 19
	±2			nA max	
Channel On Leakage I_D, I_S (ON)	±0.1			nA typ	V_S = V_D = 1 V or 2.6 V; Figure 20
	±2			nA max	
DIGITAL INPUTS					
Input High Voltage, V_{INH}			2	V min	
Input Low Voltage, V_{INL}			0.8	V max	
Input Current I_{INL} or I_{INH}	0.005			μA typ	V_{IN} = V_{INL} or V_{INH}
			±0.1	μA max	
C_{IN}, Digital Input Capacitance	4			pF typ	
DYNAMIC CHARACTERISTICS[2]					
$t_{TRANSISTION}$	24			ns typ	R_L = 50 Ω, C_L = 35 pF
	30	32	35	ns max	V_S = 1.5 V/0 V; Figure 21
t_{ON} ENABLE	23			ns typ	R_L = 50 Ω, C_L = 35 pF
	29	30	31	ns max	V_S = 1.5 V/0 V; Figure 23
t_{OFF} ENABLE	5			ns typ	R_L = 50 Ω, C_L = 35 pF
	6	7	8	ns max	V_S = 1.5 V; Figure 23
Break-Before-Make Time Delay (t_{BBM})	20			ns typ	R_L = 50 Ω, C_L = 35 pF
			5	ns min	V_{S1} = V_{S2} = 1.5 V; Figure 22
Charge Injection	28			pC typ	V_S = 1.5 V, R_S = 0 Ω, C_L = 1 nF; Figure 24
Off Isolation	−67			dB typ	R_L = 50 Ω, C_L = 5 pF,f = 100 kHz; Figure 25
Channel-to-Channel Crosstalk	−75			dB typ	R_L = 50 Ω, C_L = 5 pF, f = 100 kHz; Figure 27
Total Harmonic Distortion (THD+N)	0.02			%	R_L = 32 Ω, f = 20 Hz to 20 kHz, V_S = 2 V p-p
Insertion Loss	0.06			dB typ	R_L = 50 Ω, C_L = 5 pF, f = 100 kHz
−3 dB Bandwidth	33			MHz typ	R_L = 50 Ω, C_L = 5 pF; Figure 26
C_S (OFF)	24			pF typ	
C_D (OFF)	105			pF typ	
C_D, C_S (ON)	125			pF typ	
POWER REQUIREMENTS					V_{DD} = 3.6 V
I_{DD}	0.003			μA typ	Digital inputs = 0 V or 3.6 V
		1.0	4	μA max	

[1] Temperature range, Y version: −40°C to +125°C.
[2] Guaranteed by design, not subject to production test.

V_{DD} = 2.5 V ± 0.2 V, GND = 0 V, unless otherwise noted.[1]

Table 2.

Parameter	+25°C	−40°C to +85°C	−40°C to +125°C	Unit	Test Conditions/Comments
ANALOG SWITCH					
Analog Signal Range			0 V to V_{DD}	V	
On Resistance (R_{ON})	0.65			Ω typ	V_{DD} = 2.3 V; V_S = 0 V to V_{DD}, I_S = 10 mA; Figure 18
	0.77	0.8	0.88	Ω max	
On Resistance Match between	0.4			Ω typ	V_{DD} = 2.3 V; V_S = 0.7 V; I_S = 10 mA
Channels (ΔR_{ON})		0.08	0.085	Ω max	
On Resistance Flatness ($R_{FLAT(ON)}$)	0.16			Ω typ	V_{DD} = 2.3 V; V_S = 0 V to V_{DD}; I_S = 10 mA
		0.23	0.24	Ω max	
LEAKAGE CURRENTS					V_{DD} = 2.7 V
Source Off Leakage I_S (OFF)	±0.1			nA typ	V_S = 1 V/2 V, V_D = 2 V/1 V; Figure 19
	±2			nA max	
Drain Off Leakage I_D (OFF)	±0.1			nA typ	V_S = 1/2 V, V_D = 2/1 V; Figure 19
	±2			nA max	
Channel On Leakage I_D, I_S (ON)	±0.1			nA typ	V_S = V_D = 1 V or 2 V; Figure 20
	±2			nA max	
DIGITAL INPUTS					
Input High Voltage, V_{INH}			1.7	V min	
Input Low Voltage, V_{INL}			0.7	V max	
Input Current I_{INL} or I_{INH}	0.005			μA typ	V_{IN} = V_{INL} or V_{INH}
			±0.1	μA max	
C_{IN}, Digital Input Capacitance	4			pF typ	
DYNAMIC CHARACTERISTICS[2]					
$T_{TRANSITION}$	25			ns typ	R_L = 50 Ω, C_L = 35 pF
	31	33	35	ns max	V_S = 1.5 V/0 V; Figure 21
t_{ON} ENABLE	25			ns typ	R_L = 50 Ω, C_L = 35 pF
	30	32	34	ns max	V_S = 1.5 V/0 V; Figure 22
t_{OFF} ENABLE	5			ns typ	R_L = 50 Ω, C_L = 35 pF
	7	8	9	ns max	V_S = 1.5 V; Figure 22
Break-Before-Make Time Delay (t_{BBM})	20			ns typ	R_L = 50 Ω, C_L = 35 pF
			5	ns min	V_{S1} = V_{S2} = 1.5 V; Figure 22
Charge Injection	20			pC typ	V_S = 1.25 V, R_S = 0 Ω, C_L = 1 nF; Figure 24
Off Isolation	−67			dB typ	R_L = 50 Ω, C_L = 5 pF, f = 100 kHz; Figure 25
Channel-to-Channel Crosstalk	−75			dB typ	R_L = 50 Ω, C_L = 5 pF, f = 100 kHz; Figure 27
Total Harmonic Distortion (THD + N)	0.022			%	R_L = 32 Ω, f = 20 Hz to 20 kHz, V_S = 1.5 V p-p
Insertion Loss	−0.06			dB typ	R_L = 50 Ω, C_L = 5 pF, f = 100 kHz
−3 dB Bandwidth	33			MHz typ	R_L = 50 Ω, C_L = 5 pF; Figure 26
C_S (OFF)	25			pF typ	
C_D (OFF)	110			pF typ	
C_D, C_S (ON)	128			pF typ	
POWER REQUIREMENTS					V_{DD} = 2.7 V
I_{DD}	0.003			μA typ	Digital inputs = 0 V or 2.7 V
		1	4	μA max	

[1] Temperature range, Y version: −40°C to +125°C.
[2] Guaranteed by design, not subject to production test.

V_{DD} = 1.65 V ± 1.95 V, GND = 0 V, unless otherwise noted.[1]

Table 3.

Parameter	+25°C	−40°C to +85°C	−40°C to +125°C	Unit	Test Conditions/Comments
ANALOG SWITCH					
Analog Signal Range			0 V to V_{DD}	V	
On Resistance (R_{ON})	1			Ω typ	V_{DD} = 1.8 V; V_S = 0 V to V_{DD}, I_S = 10 mA
	1.4	2.2	2.2	Ω max	
	2.2	4	4	Ω max	V_{DD} = 1.65 V, V_S = 0 V to V_{DD}, I_S = 10 mA; Figure 18
On Resistance Match between Channels (ΔR_{ON})	0.1			Ω typ	V_{DD} = 1.65 V, V_S = 0.7 V, I_S = 10 mA
LEAKAGE CURRENTS					V_{DD} = 1.95 V
Source Off Leakage I_S (OFF)	±0.1			nA typ	V_S = 0.6 V/1.35 V, V_D = 1.35 V/0.6 V;
	±2			nA max	Figure 19
Drain Off Leakage I_D (OFF)	±0.1			nA typ	V_S = 0.6/1.35 V, V_D = 1.35/0.6 V;
	±2			nA max	Figure 19
Channel On Leakage I_D, I_S (ON)	±0.1			nA typ	V_S = V_D = 0.6 V or 1.35 V; Figure 20
	±2			nA max	
DIGITAL INPUTS					
Input High Voltage, V_{INH}			0.65 V_{DD}	V min	
Input Low Voltage, V_{INL}			0.35 V_{DD}	V max	
Input Current I_{INL} or I_{INH}	0.005			μA typ	V_{IN} = V_{INL} or V_{INH}
			±0.1	μA max	
C_{IN}, Digital Input Capacitance	4			pF typ	
DYNAMIC CHARACTERISTICS[2]					
$t_{TRANSISTION}$	32			ns typ	R_L = 50 Ω, C_L = 35 pF
	40	42	44	ns max	V_S = 1.5 V/0 V; Figure 21
t_{ON} ENABLE	34			ns typ	R_L = 50 Ω, C_L = 35 pF
	39	40	41	ns max	V_S = 1.5 Ω/0 V; Figure 22
t_{OFF} ENABLE	8			ns typ	R_L = 50 Ω, C_L = 35 pF
	10	11	13	ns max	V_S = 1.5 V; Figure 22
Break-Before-Make Time Delay (t_{BBM})	22			ns typ	R_L = 50 Ω, C_L = 35 pF
			5	ns min	V_{S1} = V_{S2} = 1 V; Figure 22
Charge Injection	12			pC typ	V_S = 1 V, R_S = 0 V, C_L = 1 nF; Figure 24
Off Isolation	−67			dB typ	R_L = 50 Ω, C_L = 5 pF, f = 100 kHz; Figure 25
Channel-to-Channel Crosstalk	−75			dB typ	R_L = 50 Ω, C_L = 5 pF, f = 100 kHz, Figure 27
Total Harmonic Distortion (THD + N))	0.14			%	R_L = 32 Ω, f = 20 Hz to 20 kHz, V_S = 1.2 V p-p
Insertion Loss	0.08			dB typ	R_L = 50 Ω, C_L = 5 pF, f = 100 kHz
−3 dB Bandwidth	30			MHz typ	R_L = 50 Ω, C_L = 5 pF; Figure 26
C_S (OFF)	26			pF typ	
C_D (OFF)	115			pF typ	
C_D, C_S (ON)	130			pF typ	
POWER REQUIREMENTS					V_{DD} = 1.95 V
I_{DD}	0.003			μA typ	Digital inputs = 0 V or 1.95 V
		1.0	4	μA max	

[1] Temperature range, Y version: −40°C to +125°C.
[2] Guaranteed by design, not subject to production test.

ABSOLUTE MAXIMUM RATINGS

T_A = 25°C, unless otherwise noted.

Table 4.

Parameter	Rating
V_{DD} to GND	−0.3 V to +4.6 V
Analog Inputs[1]	−0.3 V to V_{DD} + 0.3 V
Digital Inputs[1]	−0.3 V to +4.6 V or 10 mA, whichever occurs first
Peak Current, S or D	(Pulsed at 1 ms, 10% Duty Cycle Max)
3.3 V Operation	500 mA
2.5 V Operation	460 mA
1.8 V Operation	420 mA
Continuous Current, S or D	
3.3 V Operation	300 mA
2.5 V Operation	275 mA
1.8 V Operation	250 mA
Operating Temperature Range	
Automotive (Y Version)	−40°C to +125°C
Storage Temperature Range	−65°C to +150°C
Junction Temperature	150°C
MSOP Package	
θ_{JA} Thermal Impedance	206°C/W
θ_{JC} Thermal Impedance	44°C/W
Lead Temperature, Soldering	As per JEDEC J-STD-020

[1] Overvoltages at IN, S, or D are clamped by internal diodes. Current should be limited to the maximum ratings given.

Stresses above those listed under Absolute Maximum Ratings may cause permanent damage to the device. This is a stress rating only; functional operation of the device at these or any other conditions above those listed in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability. Only one absolute maximum rating may be applied at any one time.

Table 5. ADG804 Truth Table

A1	A0	EN	ON Switch
x	x	0	None
0	0	1	S1
0	1	1	S2
1	0	1	S3
1	1	1	S4

ESD CAUTION

ESD (electrostatic discharge) sensitive device. Charged devices and circuit boards can discharge without detection. Although this product features patented or proprietary protection circuitry, damage may occur on devices subjected to high energy ESD. Therefore, proper ESD precautions should be taken to avoid performance degradation or loss of functionality.

PIN CONFIGURATION

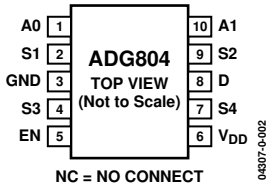

Figure 2. 10-Lead MSOP (RM-10)

Table 6. Terminology

V_{DD}	Most positive power supply potential.
I_{DD}	Positive supply current.
GND	Ground (0 V) reference.
S	Source terminal. May be an input or an output.
D	Drain terminal. May be an input or an output.
EN	Active high logic control input.
A0, A1	Logic control inputs. Used to select which source terminal, S1 to S4, is connected to the drain, D.
V_D, V_S	Analog voltage on terminals D, S.
R_{ON}	Ohmic resistance between D and S.
$R_{FLAT (ON)}$	Flatness is defined as the difference between the maximum and minimum value of on resistance as measured over the specified analog signal range.
ΔR_{ON}	On resistance match between any two channels.
I_S (OFF)	Source leakage current with the switch off.
I_D (OFF)	Drain leakage current with the switch off.
I_D, I_S (ON)	Channel leakage current with the switch on.
V_{INL}	Maximum input voltage for Logic 0.
V_{INH}	Minimum input voltage for Logic 1.
I_{INL} (I_{INH})	Input current of the digital input.
C_S (OFF)	Off switch source capacitance. Measured with reference to ground.
C_D (OFF)	Off switch drain capacitance. Measured with reference to ground.
C_D, C_S (ON)	On switch capacitance. Measured with reference to ground.
C_{IN}	Digital input capacitance.
t_{ON} (EN)	Delay time between the 50% and the 90% points of the digital input and switch on condition.
t_{OFF} (EN)	Delay time between the 50% and the 90% points of the digital input and switch off condition.
$t_{TRANSITION}$	Delay time between the 50% and the 90% points of the digital input and switch on condition when switching from one address state to the other.
t_{BBM}	On or off time measured between the 80% points of both switches when switching from one to another.
Charge Injection	A measure of the glitch impulse transferred from the digital input to the analog output during on-off switching.
Off Isolation	A measure of unwanted signal coupling through an off switch.
Crosstalk	A measure of unwanted signal which is coupled through from one channel to another as a result of parasitic capacitance.
−3 dB Bandwidth	The frequency at which the output is attenuated by 3 dB.
On Response	The frequency response of the on switch.
Insertion Loss	The loss due to the on resistance of the switch.
THD + N	The ratio of the harmonic amplitudes plus noise of a signal to the fundamental.

TYPICAL PERFORMANCE CHARACTERISTICS

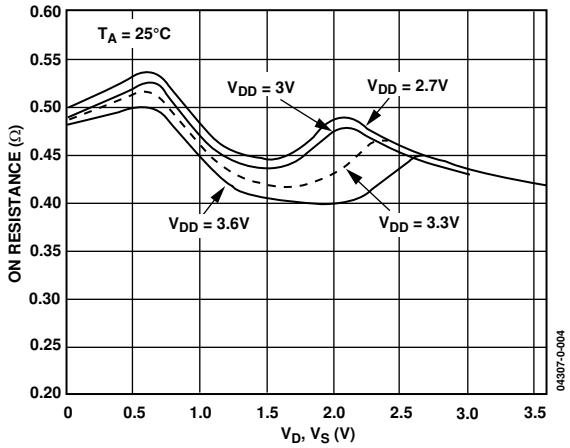

Figure 3. On Resistance vs. V_D (V_S) V_{DD} = 2.7 V to 3.6 V

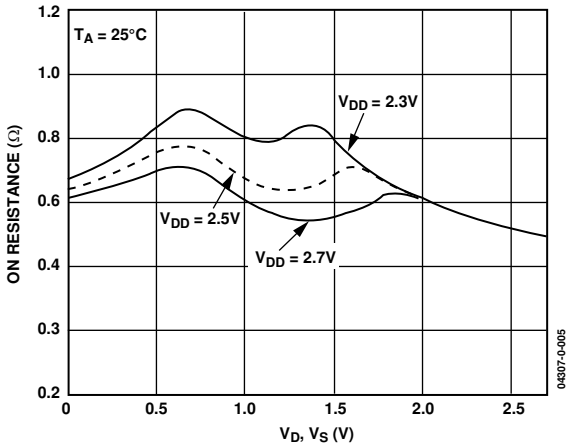

Figure 4. On Resistance vs. V_D (V_S) V_{DD} = 2.5 V ± 0.2 V

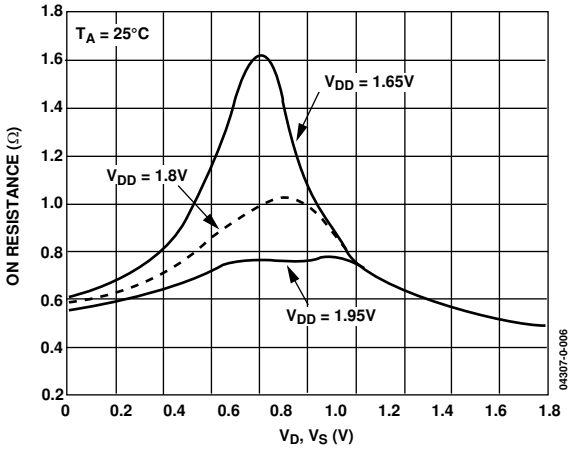

Figure 5. On Resistance vs. V_D (V_S) V_{DD} = 1.8 ± 0.15 V

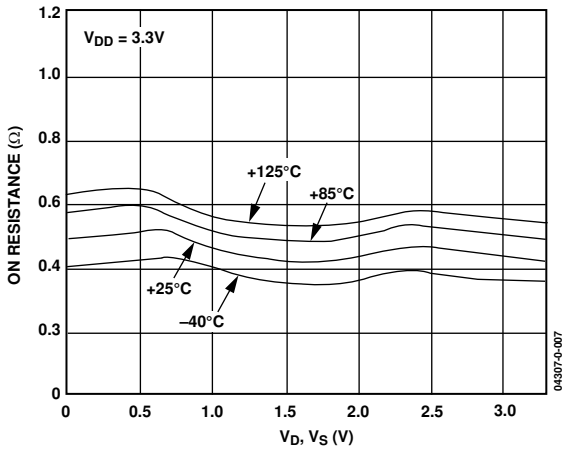

Figure 6. On Resistance vs. V_D (V_S) for Different Temperature, V_{DD} = 3.3 V

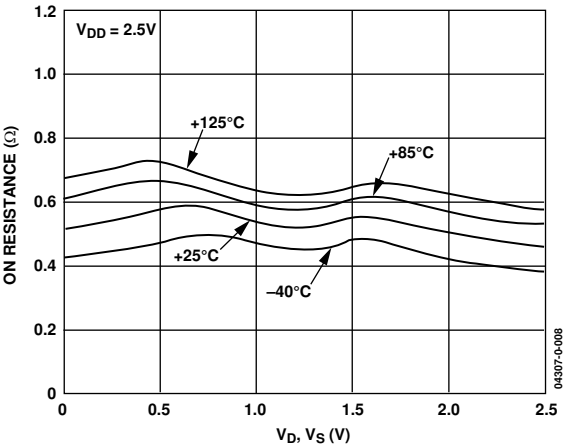

Figure 7. On Resistance vs. V_D (V_S) for Different Temperature, V_{DD} = 2.5 V

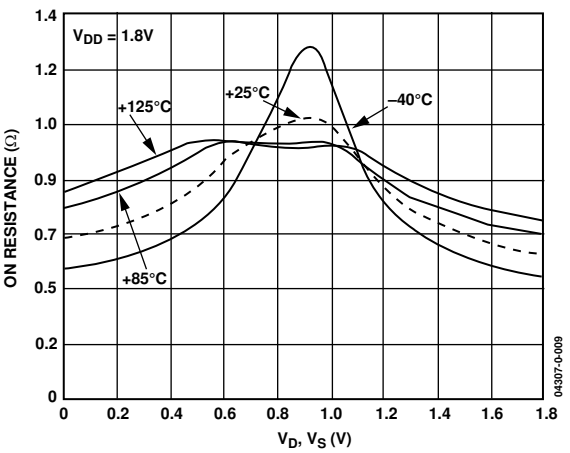

Figure 8. On Resistance vs. V_D (V_S) for Different Temperature, V_{DD} = 1.8 V

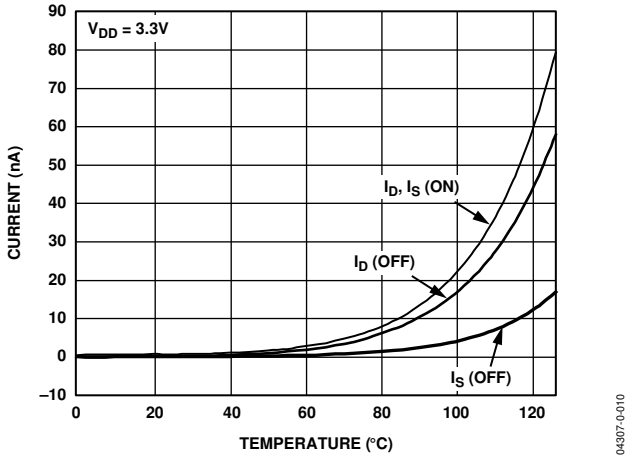

Figure 9. Leakage Current vs. Temperature, V_{DD} = 3.3 V

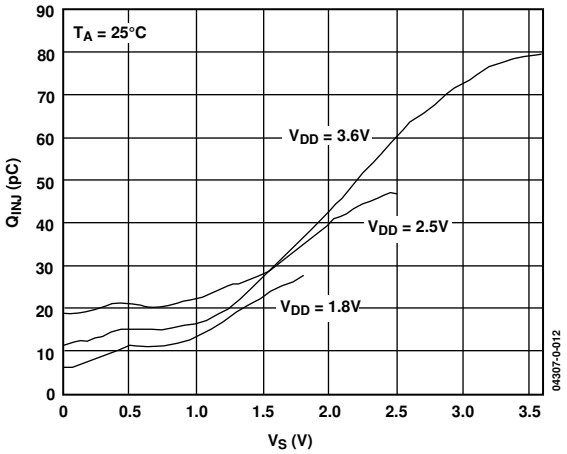

Figure 12. Charge Injection vs. Source Voltage, V_{DD} = 1.8 V

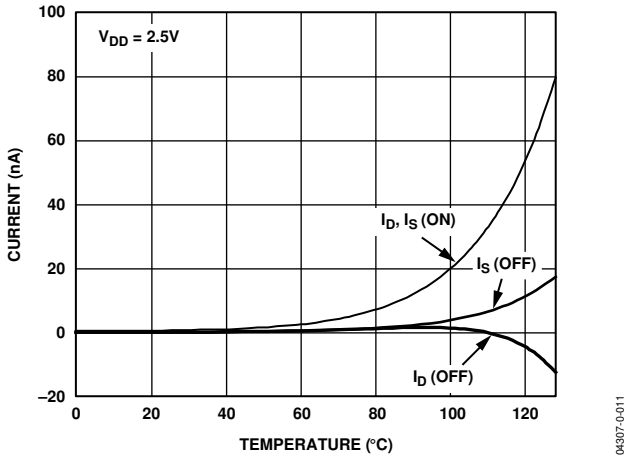

Figure 10. Leakage Current vs. Temperature, V_{DD} = 2.5 V

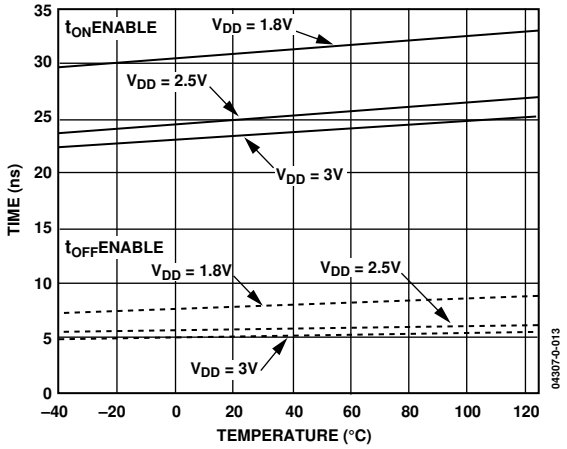

Figure 13. t_{ON}/t_{OFF} Times vs. Temperature

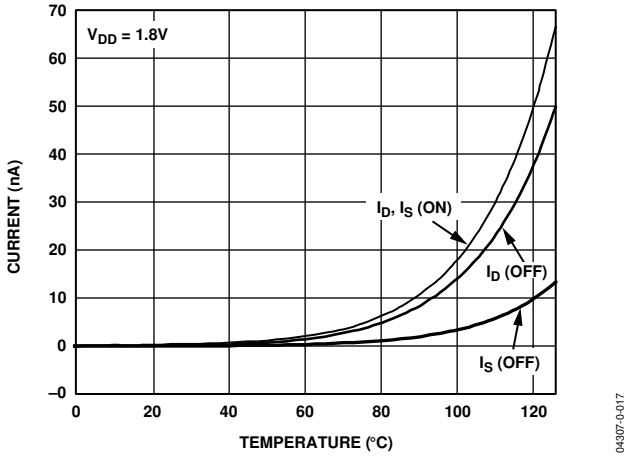

Figure 11. Leakage Current vs. Temperature, V_{DD} = 1.8 V

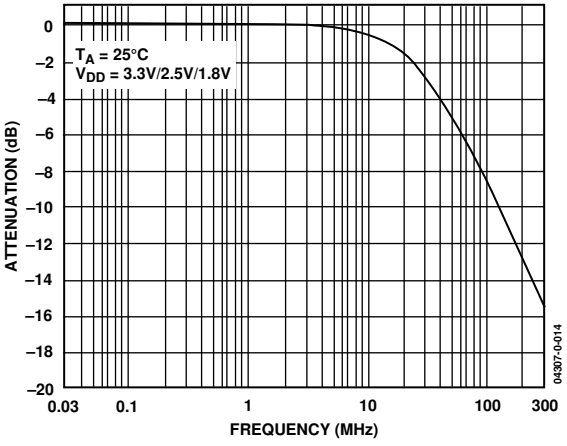

Figure 14. Bandwidth

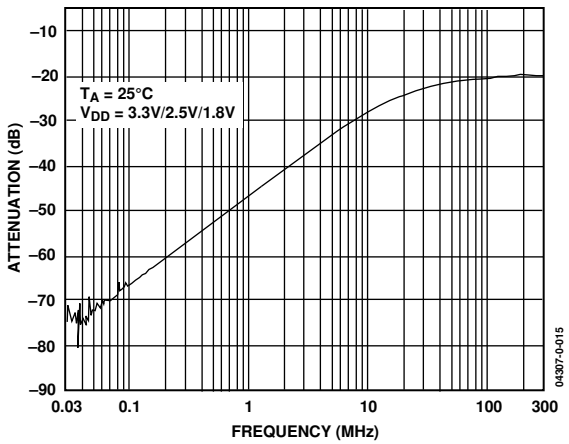

Figure 15. Off Isolation vs. Frequency

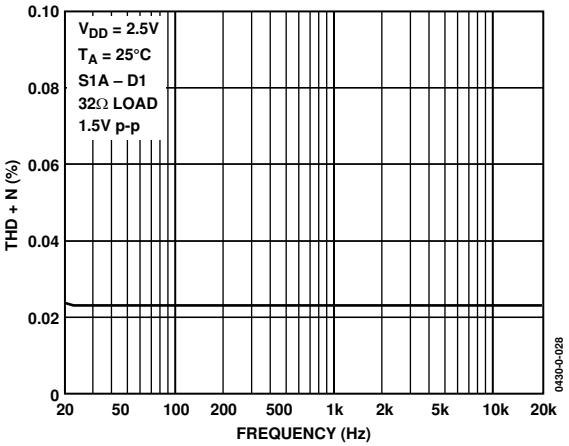

Figure 17. Total Harmonic Distortion + Noise

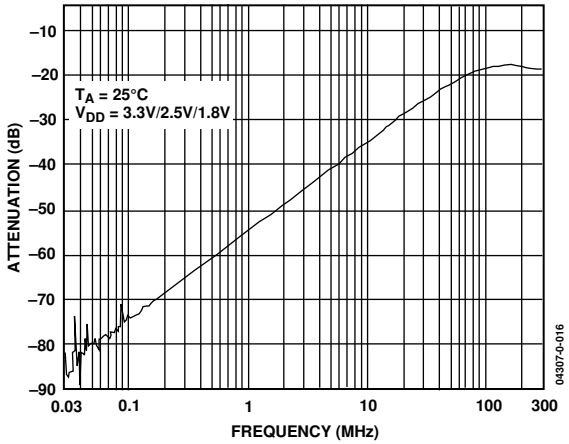

Figure 16. Crosstalk vs. Frequency

TEST CIRCUITS

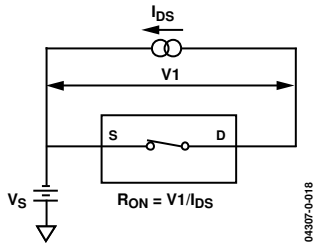

Figure 18. On Resistance

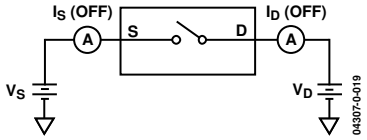

Figure 19. Off Leakage

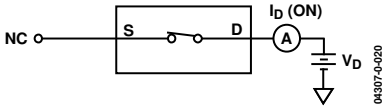

Figure 20. On Leakage

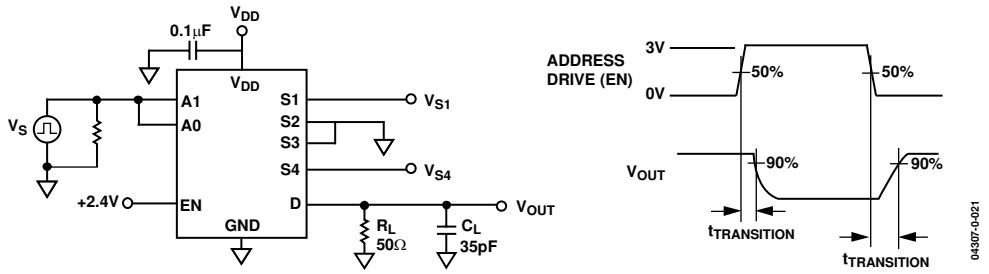

Figure 21. Switching Time of Multiplexer, $t_{TRANSITION}$

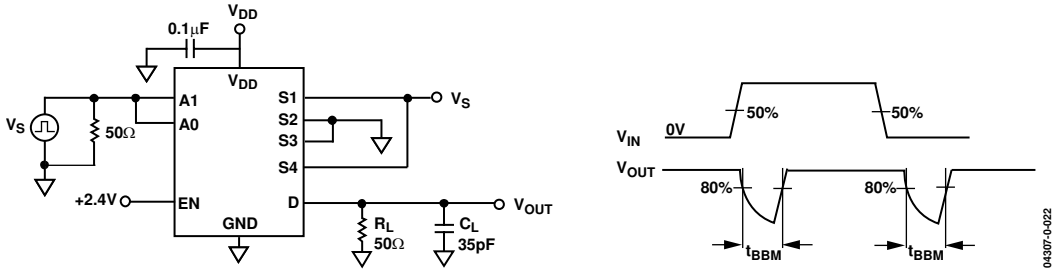

Figure 22. Break-Before-Make Time Delay, t_{BBM}

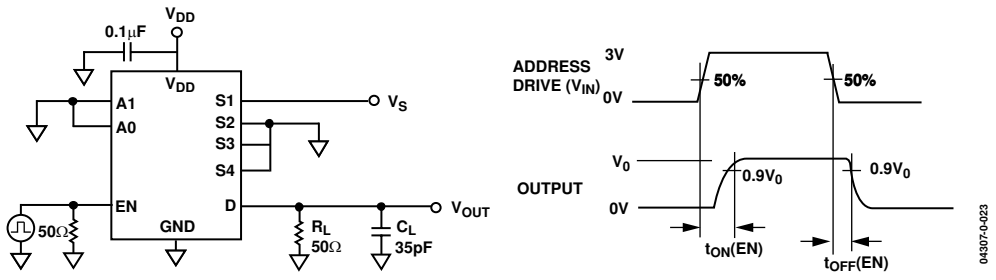

Figure 23. Enable Delay, $t_{ON}(EN)$, $t_{OFF}(EN)$

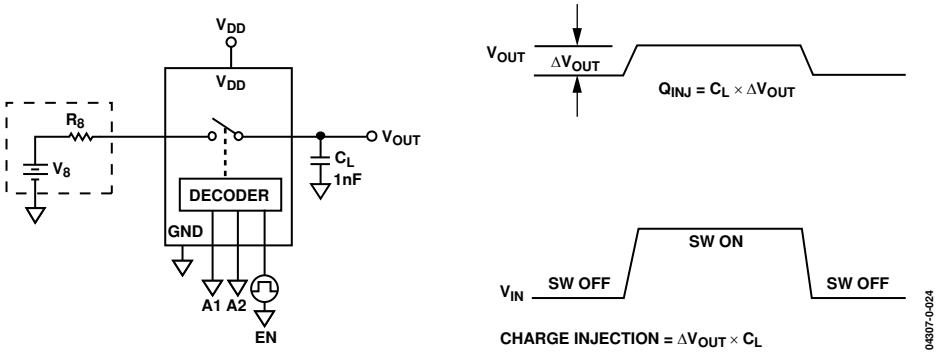

Figure 24. Charge Injection

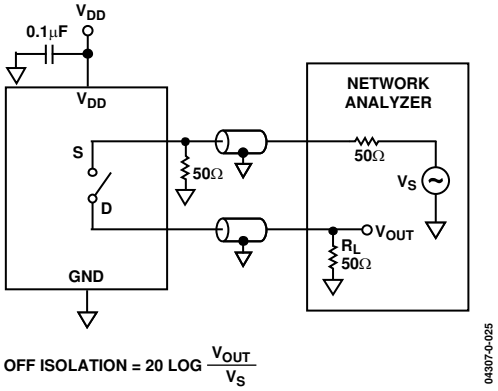

Figure 25. Off Isolation

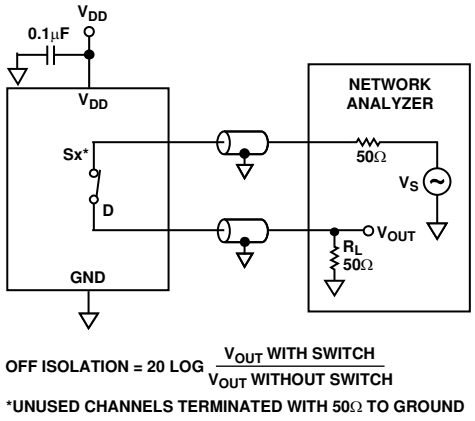

Figure 26. Bandwidth

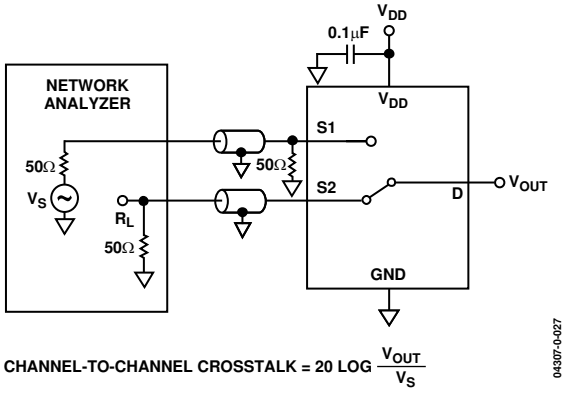

Figure 27. Channel-to-Channel Crosstalk

OUTLINE DIMENSIONS

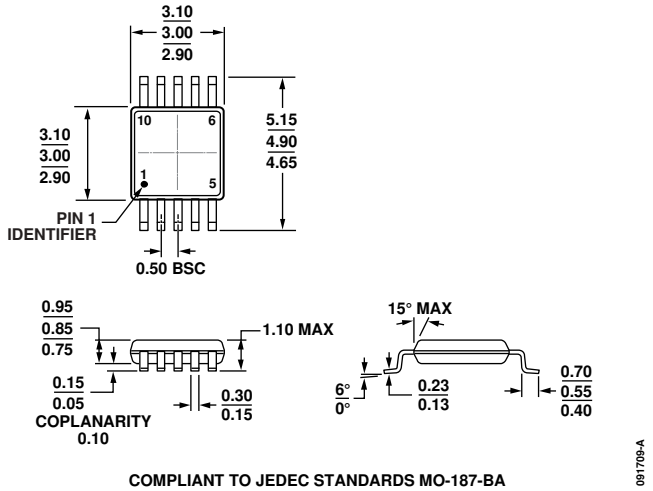

Figure 28. 10-Lead Mini Small Outline Package [MSOP]
(RM-10)
Dimensions shown in millimeters

ORDERING GUIDE

Model[1]	Temperature Range	Package Description	Package Option	Branding[2, 3]
ADG804YRM	–40°C to +125°C	10-Lead Mini Small Outline Package (MSOP)	RM-10	S1A
ADG804YRMZ	–40°C to +125°C	10-Lead Mini Small Outline Package (MSOP)	RM-10	S0N#
ADG804YRMZ-REEL	–40°C to +125°C	10-Lead Mini Small Outline Package (MSOP)	RM-10	S0N#
ADG804YRMZ-REEL7	–40°C to +125°C	10-Lead Mini Small Outline Package (MSOP)	RM-10	S0N#

[1] Z= RoHS compliant part.
[2] Branding on this package is limited to three characters due to space constraints.
[3] # denotes lead-free product may be top or bottom marked

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D04307–0–9/11(A)